

HSC119

Silicon Epitaxial Planar Diode for High Speed Switching

REJ03G0188-0100Z
(Previous: ADE-208-615)
Rev.1.00
Mar.22.2004

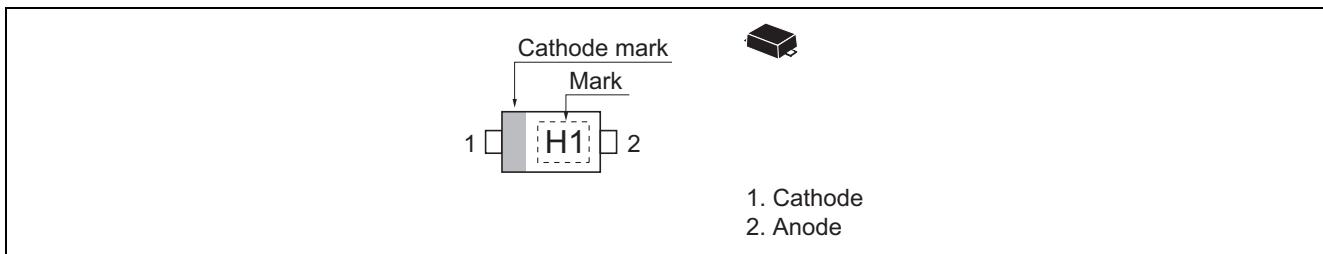
Features

- Low capacitance. ($C = 2.0$ pF max)
- Short reverse recovery time. ($t_{rr} = 3.0$ ns max)
- Ultra small Flat Package (UFP) is suitable for surface mount design.

Ordering Information

Type No.	Laser Mark	Package Code
HSC119	H1	UFP

Pin Arrangement



Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Peak reverse voltage	V_{RM}	85	V
Reverse voltage	V_R	80	V
Peak forward current	I_{FM}	300	mA
Non-Repetitive peak forward surge current	I_{FSM}^{*1}	4	A
Average rectified current	I_O	100	mA
Junction temperature	T_j	125	°C
Storage temperature	T_{stg}	-55 to +125	°C

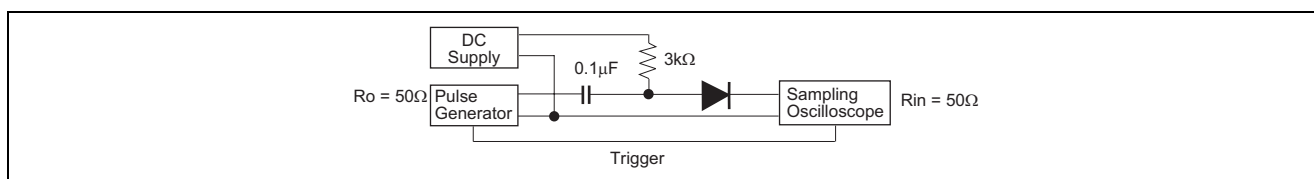
Note: 1. Within 1μs forward surge current.

Electrical Characteristics

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Forward voltage	V_{F1}	—	—	0.8	V	$I_F = 10 \text{ mA}$
	V_{F2}	—	—	1.2		$I_F = 100 \text{ mA}$
Reverse current	I_R	—	—	0.1	μA	$V_R = 80 \text{ V}$
Capacitance	C	—	—	2.0	pF	$V_R = 0 \text{ V}, f = 1 \text{ MHz}$
Reverse recovery time* ¹	t_{rr}	—	—	3.0	ns	$I_F = 10 \text{ mA}, V_R = 6 \text{ V}, R_L = 50 \Omega$

Note: 1. Reverse recovery time test circuit



Main Characteristics

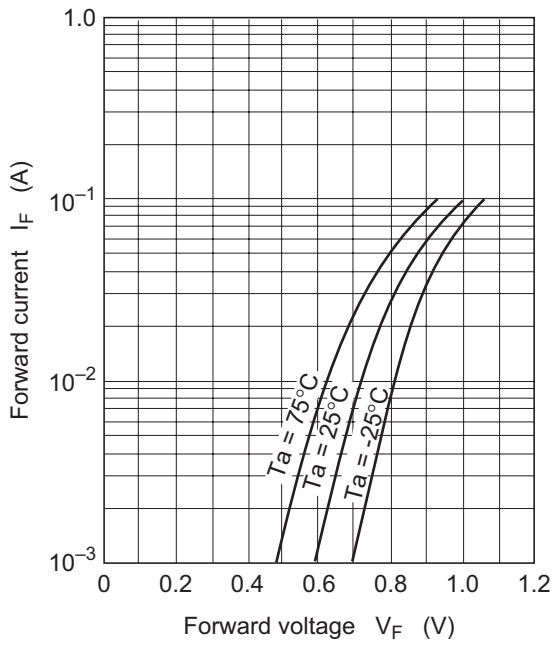


Fig.1 Forward current vs. Forward voltage

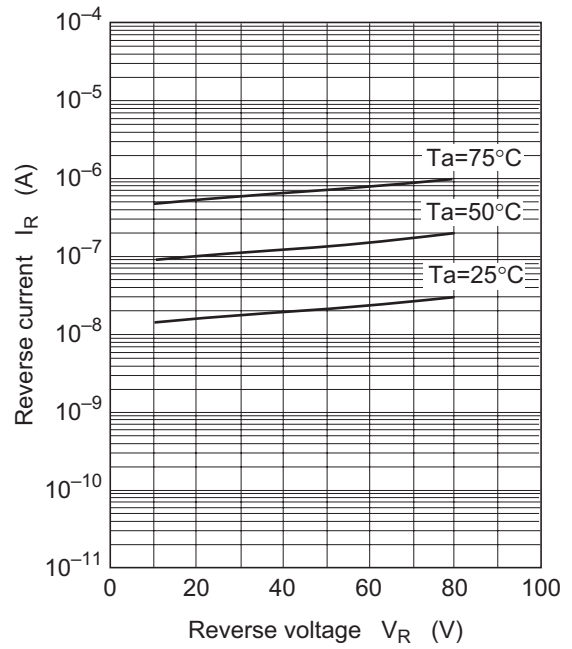


Fig.2 Reverse current vs. Reverse voltage

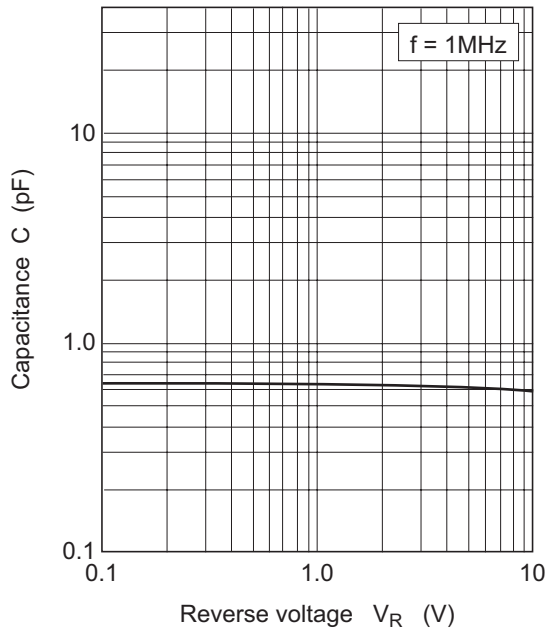
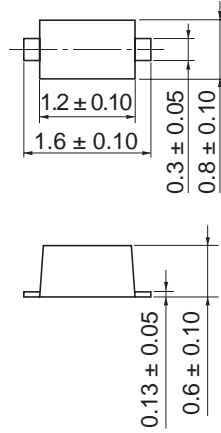


Fig.3 Capacitance vs. Reverse voltage

Package Dimensions

As of January, 2003
Unit: mm



Package Code	UFP
JEDEC	—
JEITA	Conforms
Mass (reference value)	0.0016 g

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